

Am79530/Am79531/Am79534/Am79535

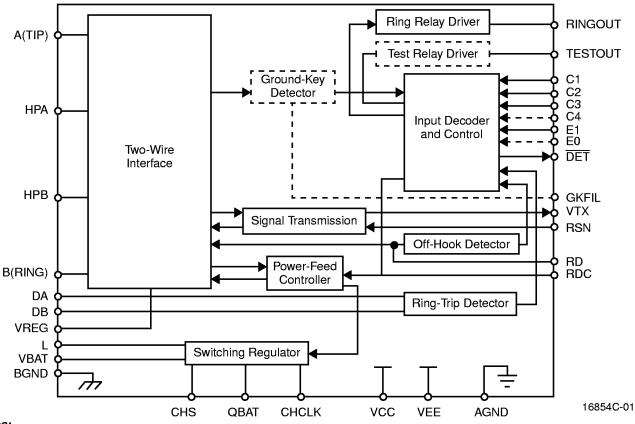
Subscriber Line Interface Circuit

DISTINCTIVE CHARACTERISTICS

- Programmable constant-current feed
- Line-feed characteristics independent of battery variations
- Programmable loop-detect threshold
- On-chip switching regulator for low-power dissipation
- Pin for external ground-key noise-filter capacitor available

- **■** Ground-key detect
- Two-wire impedance set by single external impedance
- **■** Polarity reversal feature
- Tip Open state for ground-start lines
- Test relay driver optional
- On-hook transmission

BLOCK DIAGRAM



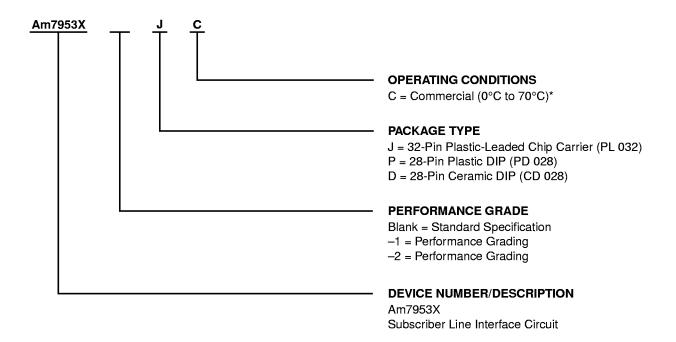
Notes:

- 1. Am79530—E0 and E1 inputs; ring relay sourced internally to BGND; no test relay driver.
- 2. Am79531—E0 and E1 inputs; ring relay sourced internally to BGND; no test relay driver; ground-key filter pin.
- 3. Am79534—E0 and E1 inputs; ring and test relay drivers sourced internally to BGND.
- 4. Am79535—E0 and E1 inputs; ring relay driver sourced internally to BGND; ground-key filter pin.
- 5. Current gain $(K_1) = 1000$ for all parts.

ORDERING INFORMATION

Standard Products

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of the elements below.



Valid Combinations								
		DC						
Am7953X	-1 -2	JC						
	_	PC						

Valid Combinations

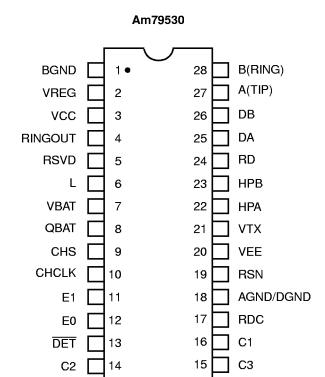
Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released combinations, and to obtain additional data on AMD's standard military grade products.

Note:

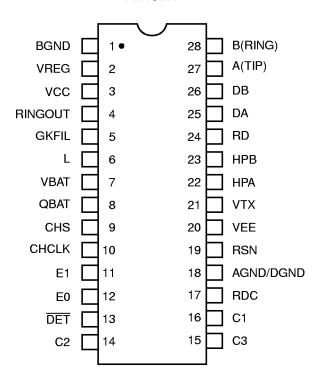
* Functionality of the device from 0° C to $+70^{\circ}$ C is guaranteed by production testing. Performance from -40° C to $+85^{\circ}$ C is guaranteed by characterization and periodic sampling of production units.

CONNECTION DIAGRAMS

Top View



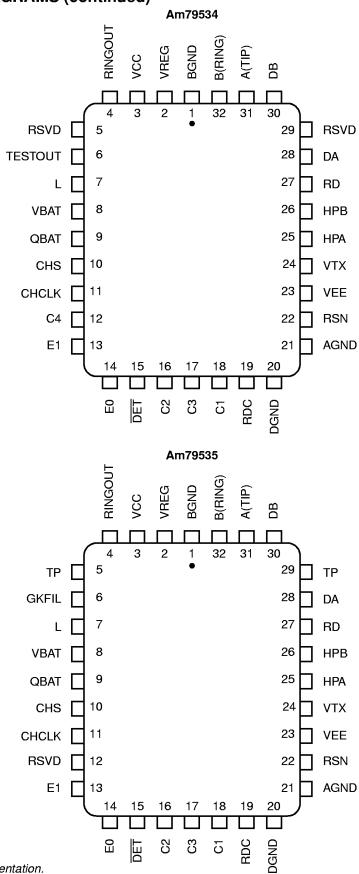
Am79531



Notes:

- 1. Pin 1 is marked for orientation.
- 2. RSVD = Reserved. Do not connect to this pin.

CONNECTION DIAGRAMS (continued)



Notes:

- 1. Pin 1 is marked for orientation.
- 2. TP is a thermal conduction pin tied to substrate (QBAT).
- 3. RSVD = Reserved. Do not connect to these pins.

PIN DESCRIPTIONS

Pin Names	Туре	Description
AGND	Gnd	(Am79534 and Am79535) Analog (quiet) ground
AGND/DGND	Gnd	(Am79530 and Am79531) Analog and Digital ground connected internally to a single pin.
A(TIP)	Output	Output of A(TIP) power amplifier.
BGND	Gnd	Battery (power) ground.
B(RING)	Output	Output of B(RING) power amplifier.
C3-C1	Inputs	Decoder. TTL compatible. C3 is MSB and C1 is LSB.
C4	Input	TTL compatible. A logic High enables the driver.
CHCLK	Input	Input to switching regulator (TTL compatible) Frequency = 256 kHz (nominal).
CHS	Input	Chopper Stabilization. Connection for external stabilization components.
DA	Input	Ring-trip negative. Negative input to ring-trip comparator.
DB	Input	Ring-trip positive. Positive input to ring-trip comparator.
DET	Output	Detector. Logic Low indicates that the selected detector is tripped. Logic inputs C3–C1, E0, and E1 select the detector. Open-collector with a built-in 15 k Ω pull-up resistor.
DGND	Gnd	(Am79534 and Am79535) Digital ground.
E0	Input	Read enable. A logic High enables DET. A logic Low disables DET.
E1	Input	E1 = High connects the ground-key detector to DET, and E1 = Low connects the off-hook or ring-trip detector to DET.
GKFIL	Capacitor	(Am79531 and Am79535) Ground-key filter capacitor. An external capacitor for filtering out high-frequency noise from the ground-key loop can be connected to this pin. An internal 36 k Ω , –20%, +40% resistor is provided to form an RC filter with the external capacitor. In versions that have a GKFIL pin, 3.3 nF minimum capacitance must be connected from the GKFIL pin to ground.
HPA	Capacitor	High-pass filter capacitor; A(TIP) side of high-pass filter capacitor.
HPB	Capacitor	High-pass filter capacitor; B(RING) side of high-pass filter capacitor.
L	Output	Switching Regulator Power Transistor. Connection point for filter inductor and anode of catch diode. Has up to 60 V pulse waveform; isolated from sensitive circuits. You must keep the diode connections short because of the high currents and high di/dt.
QBAT	Battery	Quiet battery. Filtered battery supply for the signal processing circuits.
RD	Resistor	Detector resistor. Threshold modification/filter point for the off-hook detector.
RDC	Resistor	DC feed resistor. Connection point for the DC feed current programming network, which also connects to the receiver summing node (RSN). V _{RDC} is negative for normal polarity and positive for reverse polarity.
RINGOUT	Output	Ring relay driver; sourcing from BGND with internal diode to QBAT.
RSN	Input	The metallic current (AC and DC) between A(TIP) and B(RING) = 1000 x the current into this pin. The networks that program receive gain, two-wire impedance, and feed current all connect to this node. This node is extremely sensitive. Route the 256-kHz chopper clock and switch lines away from the RSN node.
TESTOUT	Output	Test relay driver. Sourcing from BGND with internal diode to QBAT.
TP	Thermal	Thermal pin. Connection for heat dissipation. Internally connected to substrate (QBAT). Leave as open circuit or connected to QBAT. In both cases, the TP pins can connect to an area of copper on the board to enhance heat dissipation
VBAT	Battery	Battery supply through an external protection diode.
VCC	Power	+5 V power supply.
VEE	Power	-5 V power supply.
VREG	Input	Regulated voltage. Provides negative power supply for power amplifiers, connection point for inductor, filter capacitor, and chopper stabilization.
VTX	Output	Transmit Audio; Unity gain version of the A(TIP) and B(RING) metallic voltage. VTX also sources the two-wire input impedance programming network.

ABSOLUTE MAXIMUM RATINGS

Storage temperature55°C to +150°C
V_{CC} with respect to AGND/DGND–0.4 V to +7.0 V $$
$V_{\mbox{\footnotesize{EE}}}$ with respect to AGND/DGND+0.4 V to -7.0 V
V_{BAT} with respect to AGND/DGND \ldots +0.4 V to -70 V
Note: Rise time of V_{BAT} (dv/dt) must be limited to 27 V/ μ s or less when Q_{BAT} bypass = 0.33 μ F.
BGND with respect to AGND/DGND + 1.0 V to -3.0 V
A(TIP) or B(RING) to BGND:
$ \begin{array}{llllllllllllllllllllllllllllllllllll$
Current from A(TIP) or B(RING) ± 150 mA
Voltage on RINGOUT BGND to 70 V above Q_{BAT}
Voltage on TESTOUT BGND to 70 V above \mathbf{Q}_{BAT}
Current through relay drivers 60 mA
Voltage on ring-trip inputs (DA and DB) V_{BAT} to 0 V
Current into ring-trip inputs $\hdots \dots \dots \pm 10 \mbox{ mA}$
Peak current into regulator switch (L pin) 150 mA
Switcher transient peak off voltage on L pin $$ +1.0 V
C4–C1, E1, CHCLK to AGND/DGND0.4 V to (V _{CC} + 0.4 V)
Maximum power dissipation (see note) $T_A = 70^{\circ}C$
In 28-pin ceramic DIP package 2.58 W In 28-pin plastic DIP package 1.4 W In 32-pin PLCC package 1.74 W

Note: Thermal limiting circuitry on chip will shut down the circuit at a junction temperature of about 165°C. The device should never be exposed to this temperature. Operation above 145°C junction temperature may degrade device reliability. See the SLIC Packaging Considerations for more information.

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient temperature 0°C to +70°C*
V _{CC} 4.75 V to 5.25 V
V _{EE}
V_{BAT}
AGND/DGND 0 V
BGND with respect to AGND/DGND100 mV to +100 mV
Load resistance on VTX to ground 10 k Ω min

Operating Ranges define those limits between which the functionality of the device is guaranteed.

^{*} Functionality of the device from $0^{\circ}C$ to $+70^{\circ}C$ is guaranteed by production testing. Performance from $-40^{\circ}C$ to $+85^{\circ}C$ is guaranteed by characterization and periodic sampling of production units.

ELECTRICAL CHARACTERISTICS

Description	Test Conditions (See	Note 1)	Min	Тур	Max	Unit	Note
Analog (V _{TX}) output impedance				3		Ω	4
Analog (V _{TX}) output offset	0°C to +70°C	-35 -30		+35 +30	mV		
	-40°C to +85°C	-1	-40 -35		+40 +35	1110	4 4
Analog (RSN) input impedance	200 Hz to 2 4 kHz			1	20	0	4
Longitudinal impedance at A or B	300 Hz to 3.4 kHz				35	Ω	
Overload level Z_{2WIN} = 600 Ω to 900 Ω	4-wire 2-wire		-3.1		+3.1	Vpk	2
Transmission Performance, 2-Wire In	npedance	•		•			
2-wire return loss (See Test Circuit D)	300 Hz to 500 Hz 500 Hz to 2.5 kHz 2.5 kHz to 3.4 kHz		26 26 20			dB	4, 10
Longitudinal Balance (2-Wire and 4-V	Vire, See Test Circuit C)						
R_L = 600 Ω Longitudinal to metallic L-T, L-4	300 Hz to 3.4 kHz	-1*	48 52				
Longitudinal to metallic L-T, L-4	200 Hz to 1 kHz: Normal polarity 0°C to +70°C Normal polarity -40°C to +85°C	-2* -2	63 58				4
	Reverse polarity 1 kHz to 3.4 kHz:	-2	54			dB	
	Normal polarity 0°C to +70°C Normal polarity -40°C to +85°C	-2* -2	58 54				4
	Reverse polarity	-2	54				
Longitudinal signal generation 4-L	300 Hz to 800 Hz 300 Hz to 800 Hz	-1*	40 42				
Longitudinal current capability per wire	Active state OHT state			25 18		mArms	4
Insertion Loss (2- to 4-Wire and 4- to	2-Wire, See Test Circuits	s A and B)		•	•		
Gain accuracy	0 dBm, 1 kHz 0°C to +70°C 0 dBm, 1 kHz		-0.15		+0.15		
	-40°C to +85°C 0 dBm, 1 kHz		-0.20		+0.20		4
	0°C to +70°C 0 dBm, 1 kHz -40°C to +85°C	-1* -1	-0.1 -0.15		+0.1		4
Variation with frequency	300 Hz to 3.4 kHz (relative to 1 kHz):	<u> </u>	0.10		+0.13	dB	7
	0°C to +70°C -40°C to +85°C		-0.1 -0.15		+0.1 +0.15		4
Gain tracking	+7 dBm to -55 dBm: 0°C to +70°C -40°C to +85°C		-0.1 -0.15		+0.1 +0.15		4

Note:

^{*} P.G. = Performance Grade (-2 performance parameters are equivalent to -1 performance parameters, except where indicated).

ELECTRICAL CHARACTERISTICS (continued)

Description	Test Conditions (See Not	e 1)	Min	Тур	Max	Unit	Note
Balance Return Signal (4- to 4-Wire	, See Test Circuit B)						
Gain accuracy	0 dBm, 1 kHz 0°C to +70°C 0 dBm, 1 kHz		-0.15		+0.15		
	-40°C to +85°C 0 dBm, 1 kHz 0°C to +70°C	–1 *	-0.20 -0.1		+0.20		4
	0 dBm, 1 kHz -40°C to +85°C	-1	-0.15		+0.15	٩D	4
Variation with frequency	300 Hz to 3.4 kHz (relative to 1 kHz):					dB	
	0°C to +70°C -40°C to +85°C		-0.1 -0.15		+0.1 +0.15		4
Gain tracking	+7 dBm to -55 dBm: 0°C to +70°C		-0.1		+0.1		4
	-40°C to +85°C		-0.15		+0.15		4
Group delay	f = 1 kHz			5.3		μs	4
Total Harmonic Distortion (2- to 4-V		ircuits	A and B)				Γ
Total harmonic distortion	0 dBm, 300 Hz to 3.4 kHz +9 dBm, 300 Hz to 3.4 kHz			-64 -55	-50 -40	dB	
Idle Channel Noise							
C-message weighted noise	2-wire: 0°C to +70°C 2-wire: 0°C to +70°C 2-wire: -40°C to +85°C	-1*		+7 +7 +7	+15 +12 +15	ID 0	4
	4-wire 0°C to +70°C 4-wire 0°C to +70°C 4-wire -40°C to +85°C	-1*		+7 +7 +7	+15 +12 +15	dBrnC	4
Psophometric weighted noise	2-wire 0°C to +70°C 2-wire 0°C to +70°C 2-wire -40°C to +85°C	-1*		-83 -83 -83	-75 -78 -75		7
	4-wire 0°C to +70°C 4-wire 0°C to +70°C 4-wire -40°C to +85°C	-1*		-83 -83 -83	-75 -78 -75	dBmp	7
Single Frequency Out-of-Band Nois	se (See Test Circuit E)						
Metallic	4 kHz to 9 kHz 9 kHz to 1 MHz 256 kHz and harmonics			-76 -76 -57		10	4, 5, 9 4, 5, 9 4, 5
Longitudinal	1 kHz to 15 kHz Above 15 kHz 256 kHz and harmonics			-70 -85 -57		dBm	4 4, 5, 9 4, 5
DC Feed Currents (See Figure 1) BA	AT = -48 V			ı	1	1	l
Active state loop-current accuracy	I _{LOOP} (nominal) = 40 mA		-7.5		+7.5	%	
OHT state	R _L = 600 Ω		18	20	22		
Tip Open state	R _L = 600 Ω				1.0	_	
Open Circuit state	R _L = 0 Ω				1.0	mA	
Fault current limit, I _L LIM (I _{AX} + I _{BX})	A and B shorted to GND				130		

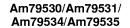
ELECTRICAL CHARACTERISTICS (continued)

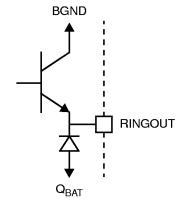
Dn-hook OHT state	Description	Test Conditions (See Note 1)	Min	Тур	Max	Unit	Note
Dn-hook OHT state	Power Dissipation BAT = -48 V , No	ormal Polarity					
Dn-hook Active state	On-hook Open Circuit state	-1*			1		
Diff-hook OHT state Pi_E 600 Ω Sou Sou	On-hook OHT state	-1*			1		
Diff-hook Active state Pile 600 Ω 650 1000	On-hook Active state	-1*				mW	
Supply Currents Voc on-hook supply current Open Circuit state OHT state Active state 7.5 12.0	Off-hook OHT state	R _L = 600 Ω		500	750	•	
Open Circuit state OHT state Active state OHT state Active state OHT state Active state 0.0	Off-hook Active state	R _L = 600 Ω		650	1000	•	
OHT state Active state Common	Supply Currents			•			
OHT state Active state 2.2 3.5 mA	V _{CC} on-hook supply current	OHT state Active state		6.0 7.5	10.0 12.0		
OHT state Active state 3.0 6.0	V _{EE} on-hook supply current	OHT state		2.2	3.5	mA	
So Hz to 3.4 kHz	V _{BAT} on-hook supply current	OHT state		3.0	5.0		
-1* 30 45	Power Supply Rejection Ratio (V_R	_{PPLE} = 50 mVrms)					
Nat	V _{cc}		1				
Comparison of the property		 	1				
3.4 kHz to 50 kHz	V_{EE}		1			dВ	6.7
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		 	1	1		GD.	0, 7
Off-Hook Detector Current threshold accuracy $I_{DET} = 365/R_D$ nominal -20 $+20$ % Ground-Key Detector Thresholds, Active State, BAT = -48 V (See Test Circuit F) Ground-key resistance threshold B(RING) to GND 2.0 5.0 10.0 $k\Omega$ Ground-key current threshold B(RING) to GND Midpoint to GND 9 mA 8 Ring-Trip Detector Input Bias current -5 -0.05 μA	V_{BAT}						
Current threshold accuracy $I_{DET} = 365/R_D$ nominal -20 $+20$ % Ground-Key Detector Thresholds, Active State, BAT = -48 V (See Test Circuit F) Ground-key resistance threshold $B(RING)$ to GND 2.0 5.0 10.0 $k\Omega$ Ground-key current threshold $B(RING)$ to GND 9 mA 8 Ring-Trip Detector Input Bias current -5 -0.05 μA			1				
Ground-Key Detector Thresholds, Active State, BAT = -48 V (See Test Circuit F) Ground-key resistance threshold Ground-key current threshold B(RING) to GND Midpoint to GND Midpoint to GND Ring-Trip Detector Input Bias current -5 -0.05 μ A	Off-Hook Detector		•		•		
Ground-key resistance threshold $B(RING)$ to GND 2.0 5.0 10.0 $k\Omega$ Ground-key current threshold $B(RING)$ to GND g	Current threshold accuracy	I _{DET} = 365/R _D nominal	-20		+20	%	
Ground-key current threshold B(RING) to GND Midpoint to GND 9 mA 8 Ring-Trip Detector Input Bias current -5 -0.05 μA	Ground-Key Detector Thresholds,	Active State, BAT = -48 V (See Test	Circuit F)				
Midpoint to GND Ring-Trip Detector Input Bias current -5 -0.05 μA	Ground-key resistance threshold	B(RING) to GND	2.0	5.0	10.0	kΩ	
Bias current -5 -0.05 μA	Ground-key current threshold			9		mA	8
	Ring-Trip Detector Input		•	•	•	-	•
Offset voltage Source resistance 0 to 2 M Ω -50 0 +50 mV 11	Bias current		-5	-0.05		μΑ	
	Offset voltage	Source resistance 0 to 2 $M\Omega$	-50	0	+50	mV	11

ELECTRICAL CHARACTERISTICS (continued)

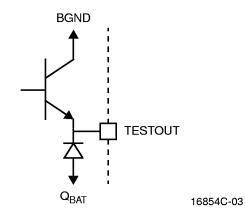
Description	Test Conditions (See Note 1)	Min	Тур	Max	Unit	Note
Logic Inputs (C4-C1, E0, E1,	and CHCLK)	•				
Input High voltage		2.0			v	
Input Low voltage				0.8	'	
Input High current	All inputs except E1 Input E1	-75 -75		40 45	μА	
Input Low current		-0.4			mA	
Logic Output (DET)		•				•
Output Low voltage	I _{OUT} = 0.8 mA			0.4	v	
Output High voltage	I _{OUT} = -0.1 mA	2.4			'	
Relay Driver Outputs (RINGC	OUT, TESTOUT)	•		•	•	
On voltage	50 mA source	BGND – 2	BGND – 0.95		٧	
Off leakage			0.5	100	μА	
Clamp voltage	50 mA sink	Q _{BAT} – 2			٧	

RELAY DRIVER SCHEMATICS





Am79534



SWITCHING CHARACTERISTICS

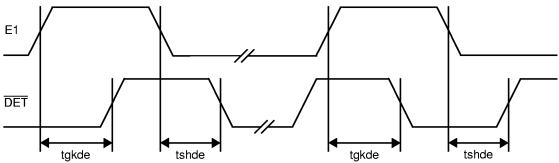
Am79530/Am79531/Am79534/Am79535

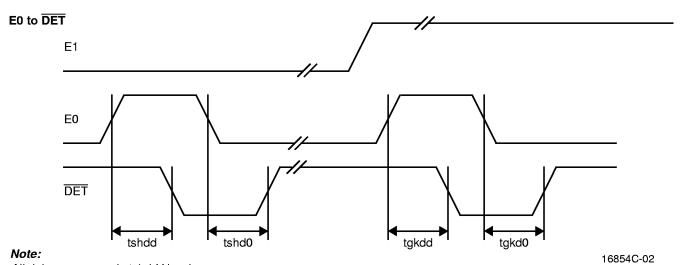
Symbol	Parameter	Test Conditions	Temperature Range	Min	Тур	Max	Unit	Note
tgkde	E1 Low to DET High (E0 = 1)		0°C to +70°C -40°C to +85°C			3.8 4.0 1.1 1.6 1.1 1.6 3.8 4.0 1.2 1.7 3.8 4.0 1.1 1.6		
	E1 Low to DET Low (E0 = 1)	Ground-key Detect state R _I open, R _G connected	0°C to +70°C -40°C to +85°C					
tgkdd	E0 High to DET Low (E1 = 0)	(See Figure H)	0°C to +70°C -40°C to +85°C					
tgkd0	E0 Low to DET High (E1 = 0)		0°C to +70°C -40°C to +85°C					4
tshde	E1 High to DET Low (E0 = 1)		0°C to +70°C -40°C to +85°C			1	μ5	4
	E1 High to DET High (E0 = 1)	Switchhook Detect state $R_1 = 600 \Omega$, R_G open	0°C to +70°C -40°C to +85°C					
tshdd	E0 High to DET Low (E1 = 1)	(See Figure G)	0°C to +70°C -40°C to +85°C					
tshd0	E0 Low to DET High (E1 = 1)		0°C to +70°C -40°C to +85°C			3.8 4.0		

SWITCHING WAVEFORMS

Am79530/Am79531/Am79534/Am79535

E1 to DET

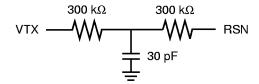




All delays measured at 1.4 V level.

Notes:

- Unless otherwise noted, test conditions are BAT = -48 V, V_{CC} = +5 V, V_{EE} = -5 V, R_L = 600 Ω, C_{HP} = 0.22 μF, R_{DC1} = R_{DC2} = 31.25 kΩ, C_{DC} = 0.1 μF, R_D = 51.1 kΩ, no fuse resistors, two-wire AC output impedance, programming impedance (Z_T) = 600 kΩ resistive, receive input summing impedance (Z_{RX}) = 300 kΩ resistive. (See Table 2 for component formulas.)
- 2. Overload level is defined when THD = 1%.
- 3. Balance return signal is the signal generated at V_{TX} by V_{RX} . This specification assumes the two-wire AC load impedance matches the impedance programmed by Z_T .
- 4. Not tested in production. This parameter is guaranteed by characterization or correlation to other tests.
- 5. These tests are performed with a longitudinal impedance of 90 Ω and metallic impedance of 300 Ω for frequencies below 12 kHz and 135 Ω for frequencies greater than 12 kHz. These tests are extremely sensitive to circuit board layout.
- 6. This parameter is tested at 1 kHz in production. Performance at other frequencies is guaranteed by characterization.
- 7. When the SLIC is in the Anti-sat 2 operating region, this parameter is degraded. The exact degradation depends on system design. The Anti-sat 2 region occurs at high loop resistances when $|V_{BAT}| |V_{AX} V_{BX}|$ is less than approximately 11 V.
- 8. "Midpoint" is defined as the connection point between two 300 Ω series resistors connected between A(TIP) and B(RING).
- 9. Fundamental and harmonics from 256 kHz switch-regulator chopper are not included.
- 10. Assumes the following Z_T network:



- 11. Tested with 0 Ω source impedance. 2 M Ω is specified for system design purposes only.
- 12. Group delay can be reduced considerably by using a Z_T network such as that shown in Note 10 above. The network reduces the group delay to less than 2 μ s. The effect of group delay on linecard performance may be compensated for by using QSLACTM or DSLACTM devices.

Table 1. SLIC Decoding

					DET Outpo	ut (E0 = 1*)
State	C 3	C2	C1	Two-Wire Status	E1 = 0	E1 = 1
0	0	0	0	Open Circuit	Ring trip	Ring trip
1	0	0	1	Ringing Ring trip Ring tri		Ring trip
2	0	1	0	Active Loop detector Gro		Ground key
3	0	1	1	On-hook TX (OHT)	Loop detector	Ground key
4	1	0	0	Tip Open	Loop detector	_
5	1	0	1	Reserved	Loop detector	_
6	1	1	0	Active Polarity Reversal	Loop detector	Ground key
7	1	1	1	OHT Polarity Reversal	Loop detector	Ground key

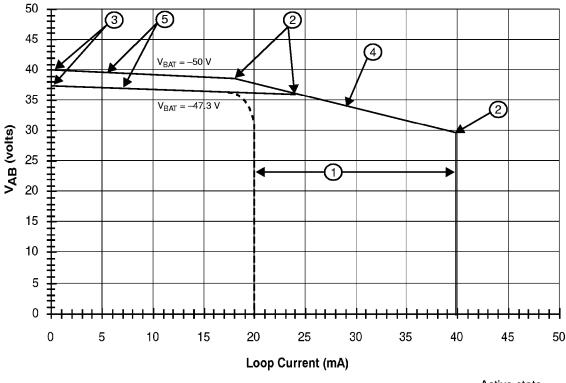
Note:

^{*} For the Am79530, Am79531, Am79534, and Am79535, a logic Low on E0 disables the DET output into the open-collector state.

Table 2. User-Programmable Components

$Z_{\rm T} = 1000(Z_{\rm 2WIN} - 2R_{\rm F})$	Where Z_T is connected between the VTX and RSN pins. The fuse resistors are R_F and Z_{2WIN} is the desired 2-wire AC input impedance. When computing Z_T , the internal current amplifier pole and any external stray capacitance between VTX and RSN must be taken into account.
$Z_{\rm RX} = \frac{Z_{\rm L}}{G_{42\rm L}} \bullet \frac{1000 \bullet Z_{\rm T}}{Z_{\rm T} + 1000(Z_{\rm L} + 2R_{\rm F})}$	Where Z_{RX} is connected from V_{RX} to the RSN pin, Z_T is defined above, and G_{42L} is the desired receive gain.
$R_{DC1} + R_{DC2} = \frac{2500}{I_{FEED}}$	Where R_{DC1} , R_{DC2} , and C_{DC} form the network connected to the RDC pin. R_{DC1} and R_{DC2} are approximately equal.
$C_{DC} = 1.5 \text{ ms} \bullet \frac{R_{DC1} + R_{DC2}}{R_{DC1} \bullet R_{DC2}}$	
$R_{\rm D} = \frac{365}{I_{\rm T}}, \qquad C_{\rm D} = \frac{0.5 \text{ ms}}{R_{\rm D}}$	Where R_D and C_D form the network connected from RD to -5 V and I_T is the threshold current between on hook and off hook.

DC FEED CHARACTERISTICS



 R_{DC} = 62.5 k Ω

_____ Active state OHT state

Notes:

1. Constant-current region:

Active state: $I_L = \frac{2500}{R_{DC}}$

OHT state: $I_L = \frac{1}{2} \bullet \frac{2500}{R_{DC}}$

2. Anti-sat turn-on (Active state):

Anti-sat -1: $V_{AB} = 29.95 \text{ V}$

Anti-sat –2: $V_{AB} = 1.082 |V_{BAT}| - 15.149$

3. Open Circuit voltage (Active state):

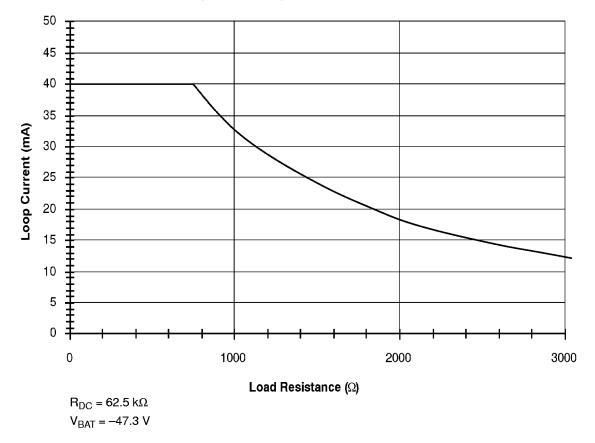
 $V_{AB} = 0.9 |V_{BAT}| - 4.995,$ $|V_{BAT}| < 56.9 \text{ V}$ $V_{AB} = 46.25 \text{ V},$ $|V_{BAT}| \ge 56.9 \text{ V}$

4. Anti-sat –1 region: $V_{AB} = 46.25 - I_L \frac{R_{DC}}{150.6}$

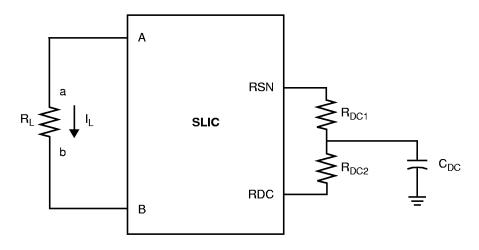
5. Anti-sat –2 region: $V_{AB} = 0.9 |V_{BAT}| - 4.995 - I_L \frac{R_{DC}}{1128}$

a. V_A–V_B (V_{AB}) Voltage vs. Loop Current (Typical)

DC FEED CHARACTERISTICS (continued)



b. Loop Current vs. Load Resistance (Typical)

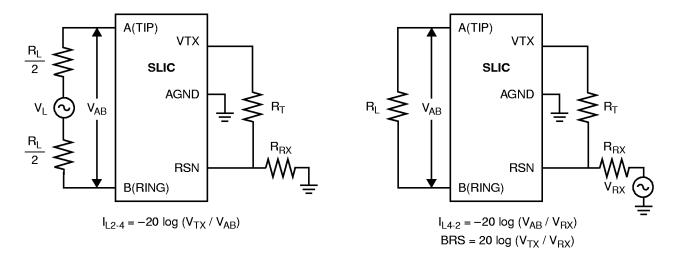


Feed current programmed by R_{DC1} and R_{DC2}

c. Feed Programming

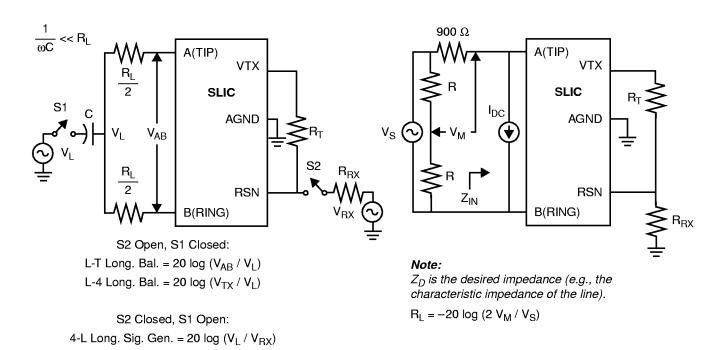
Figure 1. DC Feed Characteristics

TEST CIRCUITS



A. Two- to Four-Wire Insertion Loss

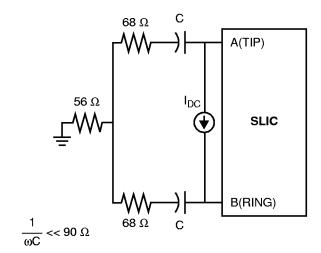
B. Four- to Two-Wire Insertion Loss and Balance Return Signal



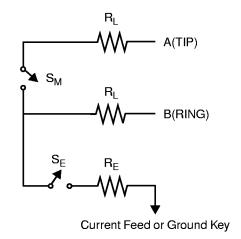
C. Longitudinal Balance

D. Two-Wire Return Loss Test Circuit

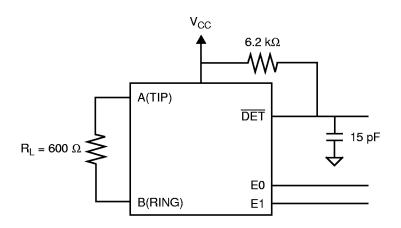
TEST CIRCUITS (continued)



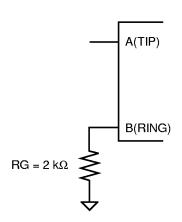
E. Single-Frequency Noise



F. Ground-Key Detection



G. Loop-Detector Switching



H. Ground-Key Switching

REVISION SUMMARY

Revision B to Revision C

- Minor changes to the data sheet style and format were made to conform to AMD standards.
- Connection Diagrams—Changed pin 29 from TP to RSVD in the Am79534 diagram.

Revision C to Revision D

- In Table 1, SLIC Decoding, the Open Circuit state of 001 was changed to 000.
- In Pin Description table, inserted/changed TP pin description to: "Thermal pin. Connection for heat dissipation. Internally connected to substrate (QBAT). Leave as open circuit or connected to QBAT. In both cases, the TP pins can connect to an area of copper on the board to enhance heat dissipation."
- · Minor changes to the data sheet style and format were made to conform to AMD standards.

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PRELIMINARY

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Count Registers

Each of the three timers has a 16-bit count register. The contents of this register may be read or written by the processor at any time. If the register is written into while the timer is counting, the new value will take effect in the current count cycle.

The count registers should be programmed before attempting to use the timers, since they are not automatically initialized to zero.

Max Count Registers

Timers 0 and 1 have two MAX COUNT registers, while Timer 2 has a single MAX COUNT register. These contain the number of events the timer will count. In timers 0 and 1, the MAX COUNT register used can alternate between the two MAX COUNT values whenever the current maximum count is reached. A timer resets when the timer count register equals the MAX COUNT value being used. If the timer count register or the MAX COUNT register is changed so that the MAX COUNT is less than the timer count the timer does not immediately reset. Instead, the timer counts up to 0FFFFH, "wraps around" to zero, counts up to the MAX COUNT value, and then resets.

Timers and Reset

Upon RESET, the Timers will perform the following actions:

- All EN (Enable) bits are reset preventing timer counting.
- For Timers 0 and 1, the RIU bits are reset to zero and the ALT bits are set to one. This results in the Timer Out pins going High.
- The contents of the count registers are indeterminate.

INTERRUPT CONTROLLER

The 80C186 can receive interrupts from a number of sources, both internal and external. The internal interrupt controller serves to merge these requests on a priority basis, for individual service by the CPU.

Internal interrupt sources (Timers and DMA channels) can be disabled by their own control registers or by mask bits within the interrupt controller. The 80C186 interrupt controller has its own control register that sets the mode of operation for the controller.

The interrupt controller will resolve priority among requests that are pending simultaneously. Nesting is provided so interrupt service routines for lower priority interrupts may themselves be interrupted by higher priority interrupts. A block diagram of the interrupt controller is shown in Figure 19.

The 80C186 has a special slave mode in which the internal interrupt controller acts as a slave to an external master. The controller is programmed into this mode by setting bit 14 in the peripheral control block relocation register (see Slave Mode section).

MASTER MODE OPERATION

Interrupt Controller External Interface

Five pins are provided for external interrupt sources. One of these pins is NMI, the non-maskable interrupt. NMI is generally used for unusual events such as power-fall interrupts. The other four pins may be configured in any of the following ways:

- As four interrupt lines with internally generated interrupt vectors.
- As an interrupt line and interrupt acknowledge line pair (cascade mode) with externally generated interrupt vectors plus two interrupt input lines with internally generated vectors.
- As two pairs of interrupt/interrupt acknowledge lines (cascade mode) with externally generated interrupt vectors.

External sources in the cascade mode use externally generated interrupt vectors. When an interrupt is acknowledged, two INTA cycles are initiated and the vector is read into the 80C 186 on the second cycle. The capability to interface to external 82C59A programmable interrupt controllers is provided when the inputs are configured in cascade mode.

Interrupt Controller Modes of Operation

The basic modes of operation of the interrupt controller in master mode are similar to the 82C59A. The interupt controller responds identically to internal interrupts in all three modes; the difference is only in the interpretation of function of the four external interrupt pins. The interrupt controller is set into one of these three modes by programming the correct bits in the INTO and INT1 control registers. The modes of interrupt controller operation are as follows:

Fully Nested Mode

When in the fully nested mode four pins are used as direct interrupt requests as in Figure 20. The vectors for these four inputs are generated internally. An in-service bit is provided for every interrupt source. If a lower-priority device requests an interrupt while the in-service bit (IS) is set, no interrupt will be generated by the interrupt controller. In addition, if another interrupt request occurs from the same interrupt source while the in-service bit is set, no interrupt will be generated by the interrupt controller. This allows interrupt service routines to operate

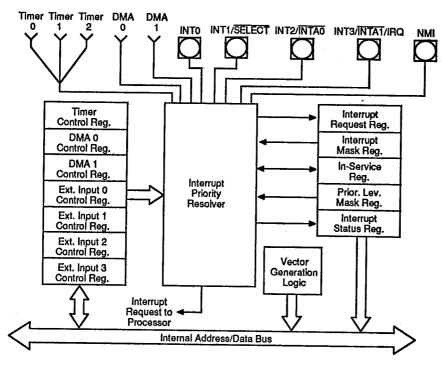


Figure 19. Interrupt Controller Block Diagram

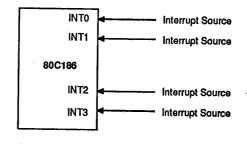
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Master Mode Features

Programmable Priority

The user can program the interrupt sources into any of eight different priority levels. The programming is done by placing a 3-bit priority level (0–7) in the control register of each interrupt source. (A source with a priority level of 4 has higher priority over all priority levels from 5 to 7. Priority registers containing values lower than 4 have greater priority.) All interrupt sources have preprogrammed default priority levels (see Table 3).

If two requests with the same programmed priority level are pending at once, the priority ordering scheme shown in Table 3 is used. If the serviced interrupt routine reenables interrupts, it allows other interrupt requests to be serviced.



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Figure 20. Fully Nested (Direct) Mode Interrupt Controller Connections

SWITCHING CHARACTERISTICS (continued)

Ready, Peripheral, and Queue Status Timings

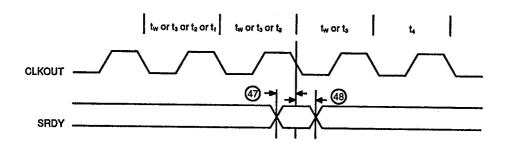
Ta = 0°C to +70°C, $V\infty = 5 V \pm 10\%$ except $V\infty = 5 V \pm 5\%$ at f > 12.5 MHz

_						Prell	minary				
			800	186	80C	186-12	80C1	86-16	80C1	8620	1-
No	Symbol	Parameter	Min	Max	Min	Max	Min	Max	Min	Max	Unit
800	C186 Rea	dy and Peripheral Timin	g Requi	rementa	,						
47	t _{srvcl}	Synchronous Ready (SRDY) Transition Setup Time ⁽¹⁾	15		15		15		10		ns
48	tousay	SRDY Transition Hold Time(1)	15		15		15		10		ns
49	tarych ,	ARDY Resolution Transition Setup Time ⁽²⁾	15		15		15		10		ns
50	tclarx	ARDY Active Hold Time(1)	15		15		15		10		ns
51	taryche	ARDY Inactive Holding Time	15		15		15		10		ns
52	LAYLCL	Asynchronous Ready (ARDY) Setup Time(1)	25		25		25		20		ns
53	t _{інусн}	INTx, NMI, TEST/BUSY, TMR IN Setup Time(a)	15		15		15		15		ns
54	tinvaL	DRQ0, DRQ1, Setup Time ⁽²⁾	15	i	15		15		15		ns
80C	186 Peri	pheral and Queue Statu	s Timing	Respor	150\$	L	1	<u> </u>			110
55	tcltmy	Timer Output Delay		40		33	T	27		25	ns
56	t _{CHOSV}	Queue Status Delay		37		32		30		23	ns

All timings are measured at 1.5 V and 100 pF loading on CLKOUT unless otherwise noted. All output test conditions are with C_L = 50–200 pF (10 MHz) and C_L = 50–100 pF (12.5–20 MHz). For AC tests, input V_R = 0.45 V and V_{H} = 2.4 V except at X_1 where V_{H} = V_{CO} = 0.5 V.

Notes: 1. To guarantee proper operation.
2. To guarantee recognition at clock edge.

Synchronous Ready (SRDY) Waveforms

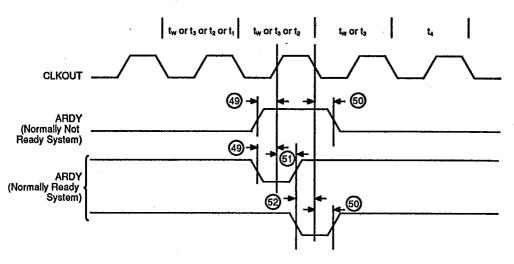


AMD

PRELIMINARY

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Asynchronous Ready (ARDY) Waveforms



Peripheral and Queue Status Waveforms

